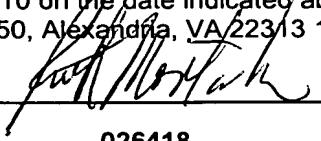


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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Attorney's Docket No.: JG-SU-5221/500577.20071

U.S. Application No.:

International Application No.: PCT/JP2004/015999

International Filing Date: OCTOBER 28, 2004 28 OCTOBER 2004

Priority Date Claimed: DECEMBER 10, 2003 10 DECEMBER 2003

Title of Invention: PROCESSING METHOD OF SILICON WAFER

Applicant(s) for (DO/EO/US): Sakae KOYATA and Kazushige TAKAISHI

Mail Stop PCT  
Commissioner for Patents  
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Alexandria, VA 22313 1450

**PRELIMINARY AMENDMENT**

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

**Amendments to the specification** begin on page 2 of this paper.

**Amendments to the Abstract** begin on page 3 of this paper.

**Remarks / Arguments** begin on page 4 of this paper.